

S/N: TBA

4/12/2001

DOCKET NO.: L/M-102-DIV

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Steve M. Danziger, et al.

Serial No.: TO BE ASSIGNED Art Unit: TO BE ASSIGNED
Divisional of 09/321,565

Filed: April 12, 2001 Examiner: TO BE ASSIGNED

For: Method and Apparatus for Evaluating a Known Good Die Using
Both Wire Bond and Flip-Chip Interconnects

J1002 U.S. PRO
09/632884
04/12/01



APPLICATION DATA SHEET

(1) APPLICANT INFORMATION

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(3) APPLICANT INFORMATION

Title Method and Apparatus for Evaluating a Known Good Die Using Both Wire Bond and Flip-Chip Interconnects
Total # Draw Sheets 6
Suggested Figure for Publication 1
Atty Docket Number L/M-102-DIV
Type of Application Utility

This case is a Divisional of USPTO Serial Number 09/321,565, filed May 28, 1999 and issuing as US Patent No. 6,221,682 on April 24, 2001.

(4) REPRESENTATIVE INFORMATION

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(5) DOMESTIC PRIORITY INFORMATION

This case is a Divisional of USPTO Serial Number 09/321,565, filed May 28, 1999 and issuing as US Patent No. 6,221,682 on April 24, 2001.

(6) FOREIGN PRIORITY INFORMATION

None

(7) ASSIGNEE INFORMATION

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